1. Economics of Circuit Edit
2. Circuit Edit flow chart
3. Sample preparation, loading and alignment
5. Choice of gas chemistries
6. Choice of apertures, beam currents, imaging modes
7. Circuitry access, via milling, dose estimation
8. Endpoint concept and detection methods
9. Via filling, conductor deposition, connections
10. Line cut, isolation on surface and in the via
11. Specifics of Cu technology
12. Interlayer isolation, dielectric deposition
13. Probe points

*Detailed syllabus is available upon request sent to: info@partbeamsystech.com